Build in Biasing Circuit MOS FET IC **UHF RF Amplifier**

HITACH

ADE-208-713A (Z) 2nd. Edition Dec. 1998

Features

- Build in Biasing Circuit; To reduce useing parts cost & PC board space.
- Low noise characteristics; (NF = 2.0 dB typ. at f = 900 MHz)
- Withstanding to ESD; Build in ESD absorbing diode. Withstand up to 200V at C=200pF, Rs=0 conditins.
- Provide mini mold packages; MPAK-4R(SOT-143 var.)

Outline

MPAK-4R



- 1. Source
- 2. Drain
- 3. Gate2
- 4. Gate 1

Notes: 1. Marking is "AV-".

2. BB201M is individual type number of HITACHI BBFET.



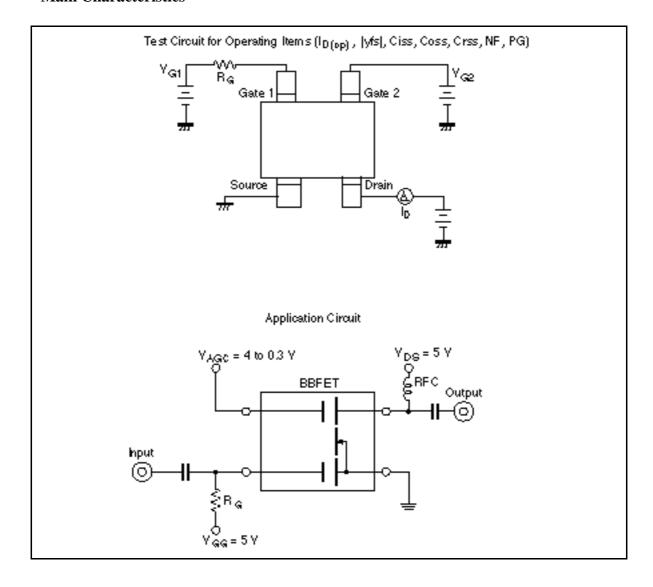
Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

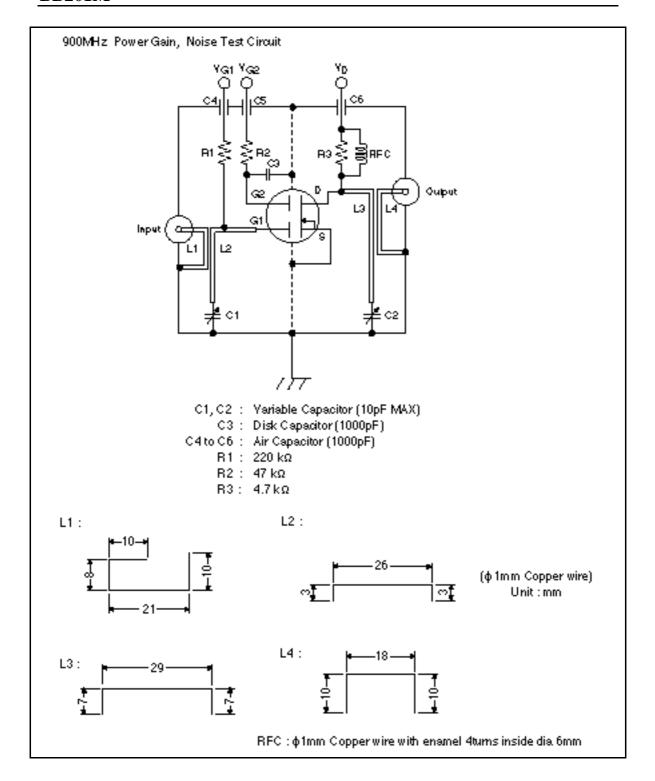
Item	Symbol	Ratings	Unit		
Drain to source voltage	V _{DS}	6	V		
Gate1 to source voltage	$V_{\sf G1S}$	+6 - 0	V		
Gate 2 to source voltage	$V_{\rm G2S}$	±6	V		
Drain current	I _D	25	mA		
Channel power dissipation	Pch	150	mW		
Channel temperature	Tch	150	°C		
Storage temperature	Tstg	-55 to +150	°C		

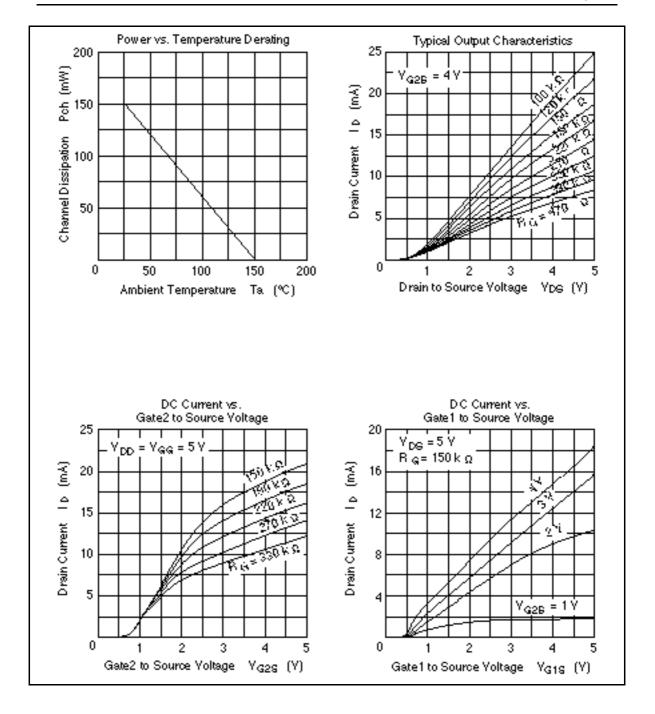
Electrical Characteristics ($Ta = 25^{\circ}C$)

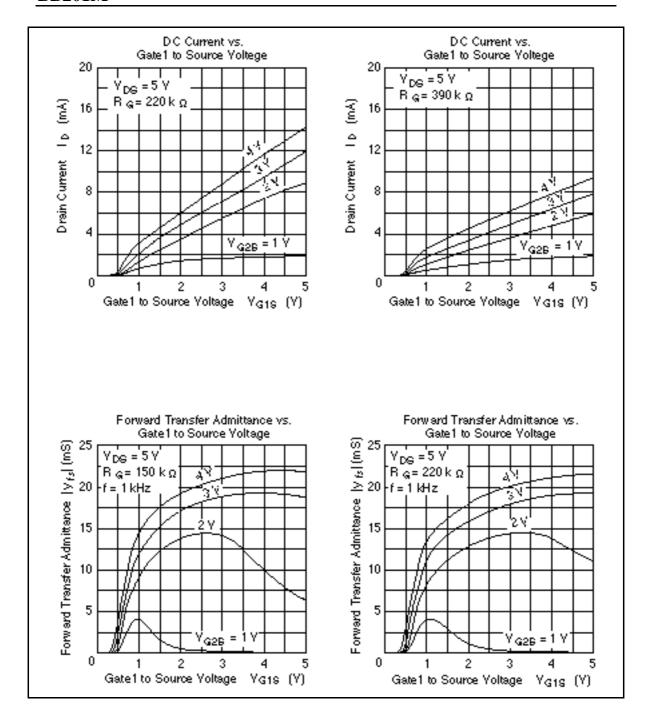
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	6	_	_	V	$I_D = 200 \mu A, V_{G1S} = V_{G2S} = 0$
Gate1 to source breakdown voltage	$V_{(BR)G1SS}$	+6	_	_	V	$I_{G1} = +10\mu A, V_{G2S} = V_{DS} = 0$
Gate2 to source breakdown voltage	$V_{(BR)G2SS}$	±6	_	_	V	$I_{G2} = \pm 10 \mu A, V_{G1S} = V_{DS} = 0$
Gate1 to cutoff current	I _{G1SS}	_	_	+100	nA	$V_{G1S} = +5V, V_{G2S} = V_{DS} = 0$
Gate2 to cutoff current	I _{G2SS}	_	_	±100	nA	$V_{G2S} = \pm 5V$, $V_{G1S} = V_{DS} = 0$
Gate1 to source cutoff voltage	$V_{\text{G1S(off)}}$	0.2	0.45	0.8	V	$V_{DS} = 5V, V_{G2S} = 4V$ $I_{D} = 100\mu A$
Gate2 to source cutoff voltage	$V_{\text{G2S(off)}}$	0.4	0.7	1.0	V	$V_{DS} = 5V, V_{G1S} = 5V$ $I_{D} = 100\mu A$
Drain current	I _{D(op)}	10	15	20	mA	$V_{DS} = 5V, V_{G1} = 5V, V_{G2S} = 4V$ $R_{G} = 220k$
Forward transfer admittance	y _{fs}	16	22	_	mS	$V_{DS} = 5V, V_{G1} = 5V, V_{G2S} = 4V$ $R_{G} = 220k$, $f = 1kHz$
Input capacitance	C _{iss}	1.2	1.7	2.2	pF	$V_{DS} = 5V, V_{G1} = 5V$
Output capacitance	C _{oss}	0.7	1.1	1.5	pF	$V_{G2S} = 4V, R_G = 220k$
Reverse capacitance	C _{rss}	_	0.012	0.03	pF	f = 1MHz
Power gain	PG	16	20		dB	$V_{DS} = 5V, V_{G1} = 5V, V_{G2S} = 4V$
Noise figure	NF	_	2.0	3.0	dB	$R_{\rm G} = 220 k$, $f = 900 MHz$

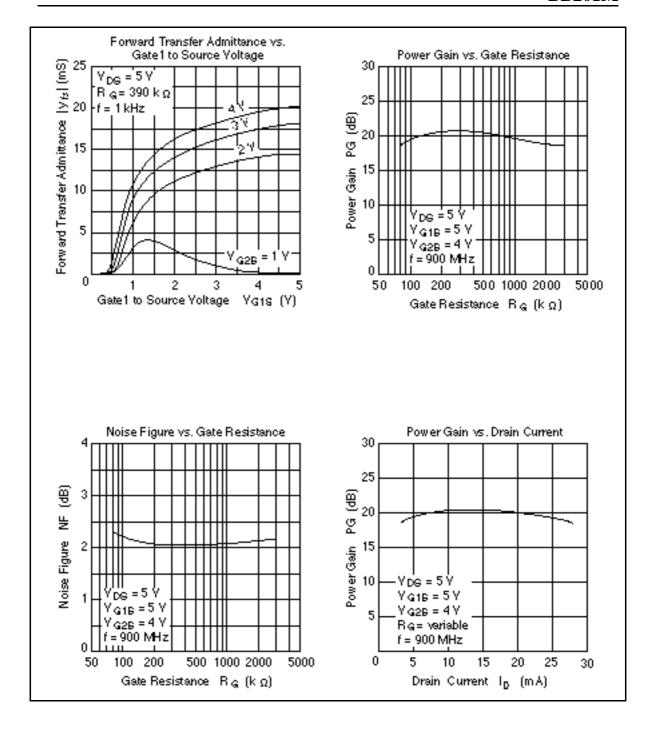
Main Characteristics

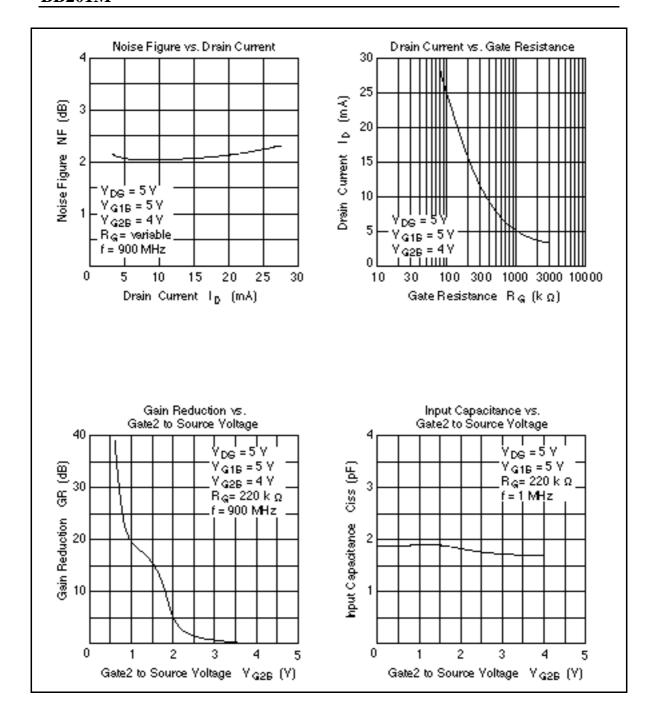


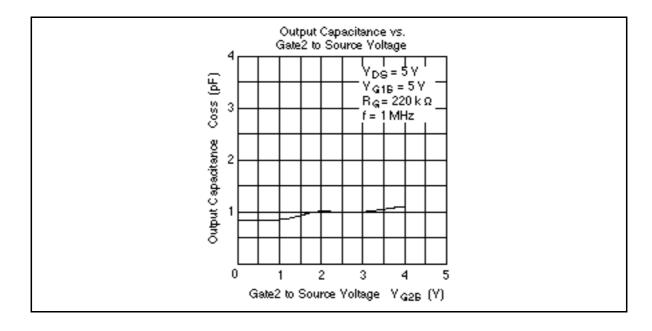






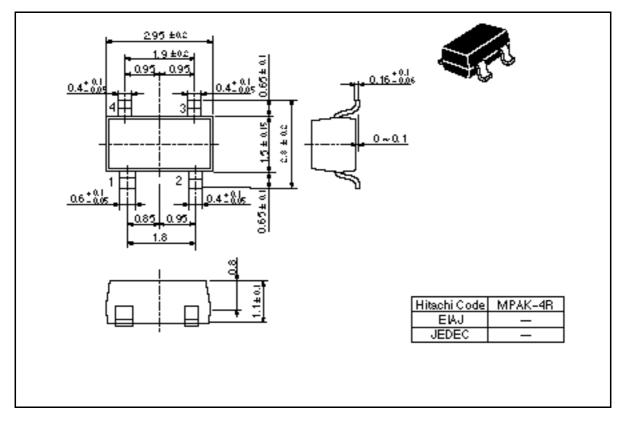






Package Dimensions

Unit: mm



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